

液晶ポリマーフィルム上への無電解銅めっき

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Electroless Copper Plating on Liquid Crystal Polymer Films

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Abstract

It is well known that liquid crystal polymer (LCP) films exhibit excellent mechanical and physical characteristics compared with those of other polymers. In order to apply LCP films on printed circuit boards, the etching conditions required for LCP film to obtain a good anchor effect for electroless copper plating was studied. After etching the LCP film in a 10M KOH solution at 70 degrees for 60-90 minutes, we obtained a copper film with excellent adhesion strength using a plating bath having slow plating speed or using sodium phosphinate as a reducing agent.

Key Words: *Liquid Crystal Polymer Film, Electroless Cu Plating, Etching, Anchor Effect, Adhesion Strength*